Opportunities and challenges in embedded systems

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Abstract

The technological advances in processing, communication, storage, actuating and sensing enables a large amount of applications of embedded systems. The challenges of today to realize these opportunities are discussed, addressing six main issues: market dynamics, interoperability, reliability, power, security, and creativity.

The capabilities of the Embedded Systems Institute are discussed briefly.

Distribution

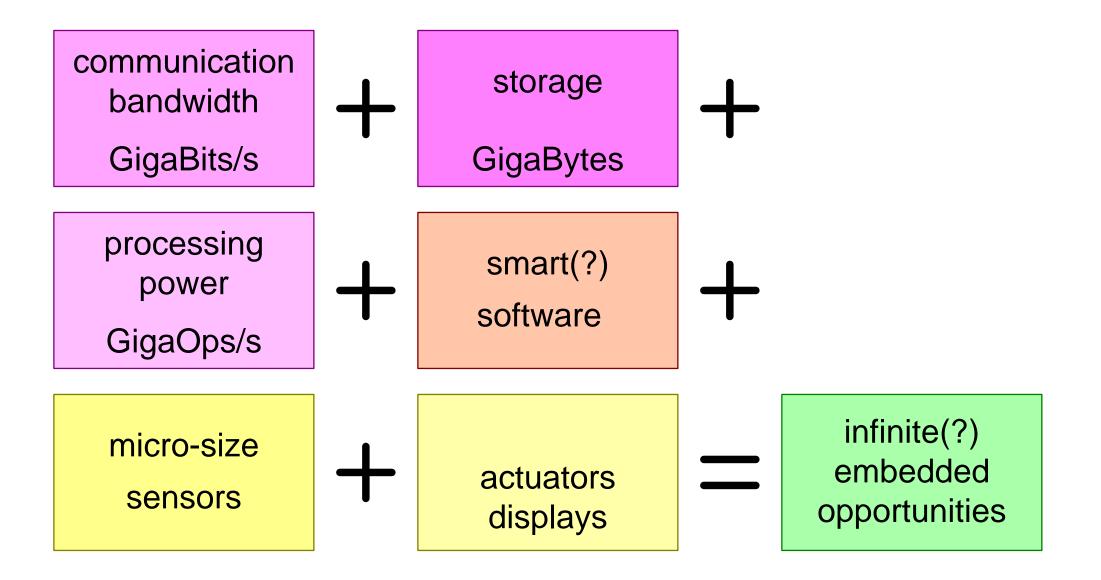
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logo **TBD**

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Giga embedded opportunities





Hit list of challenges

discover latent needs enable emergence where is the business

creativity

globalization hype waves Moore's law

market dynamics

security

privacy, DRM versus usability

interoperability

emerging behavior, future vs legacy heterogeneous vendors

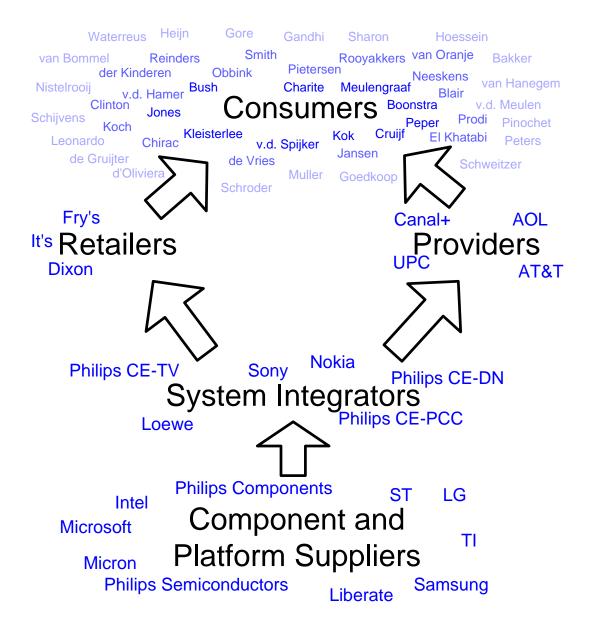
power consumption

weight, cost, performance

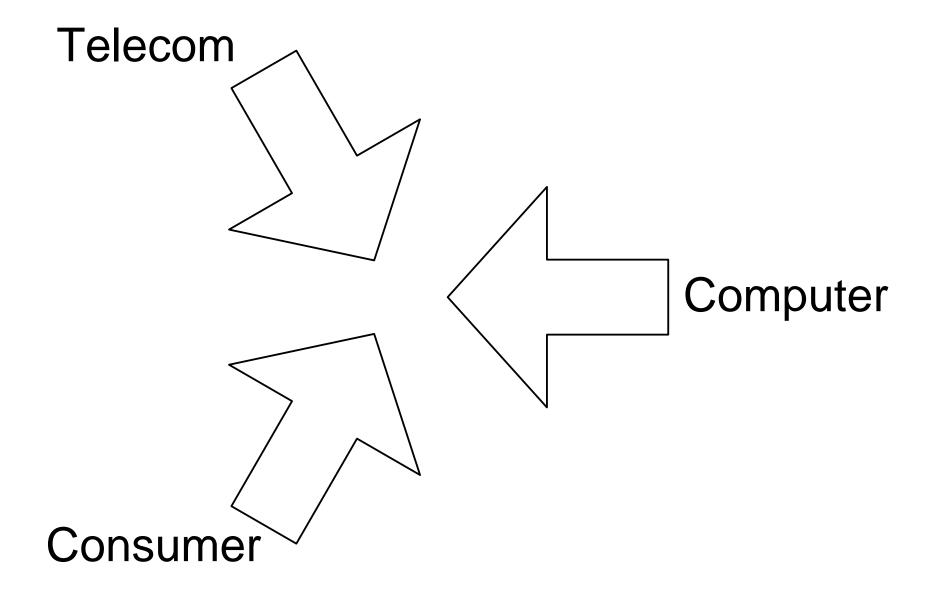
reliability complexity
heterogeneity
#engineers involved



Value Chain in Consumer Electronics







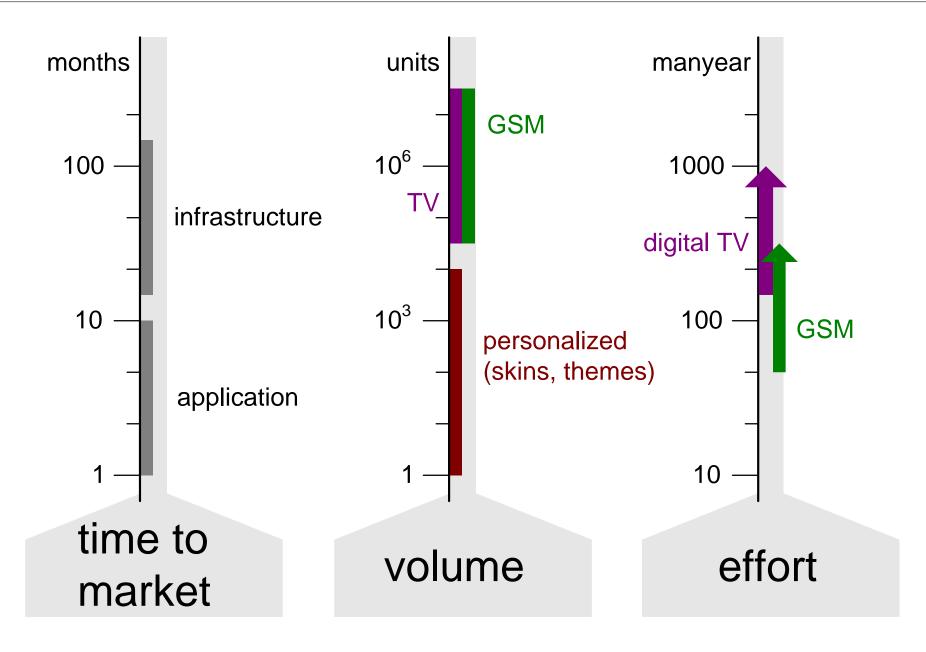


Integration and Diversity





System Integrator Problem Space - Business





Is reuse the solution to effort?

trends



- performance expectations
- number of products
- release cycle time years → months
- openness interoperability

consequences



- complexity
- amount of software
- integration effort
- reliability

solutions



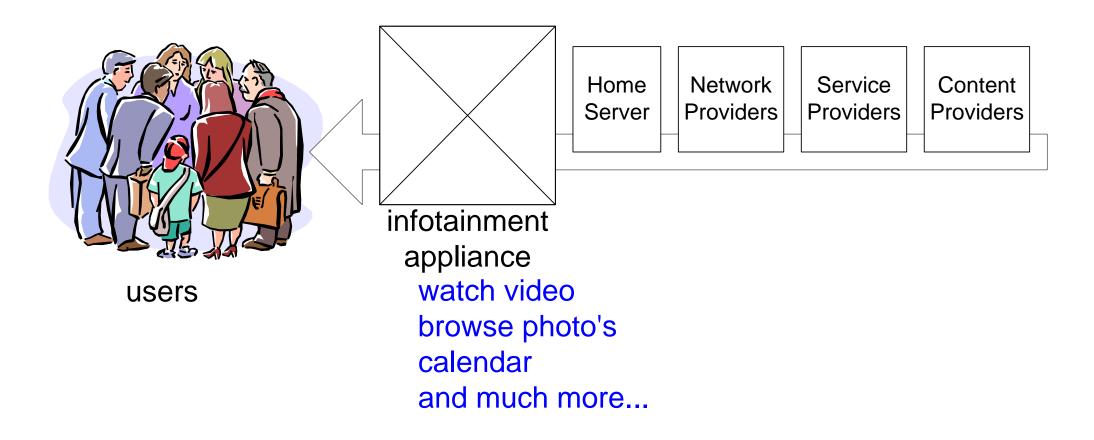


- new software technology
- new standards



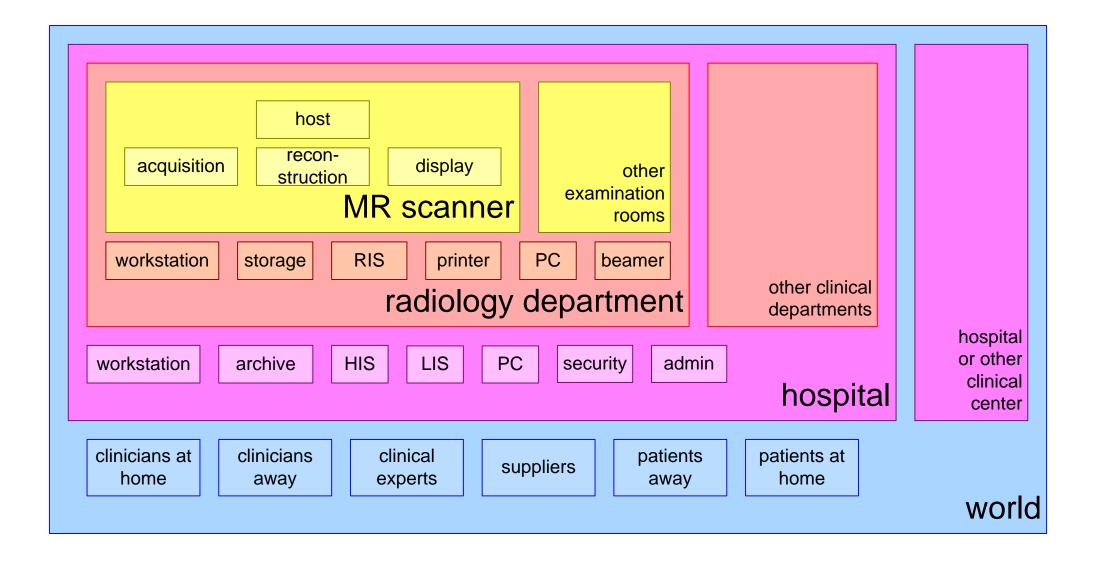


Applications depend on chain of systems





Interoperability: systems get connected at all levels





Multi dimensional interoperability

integrating multiple

applications

cilinical analysis clinical support administrative financial workflow

cultures

USA, UK, China, India, Japan, Korea France, Germany Italy, Mexico

in **multiple**

languages

delivered by multiple

vendors

Philips GE Siemens

based on multiple

media, networks

DVD+RW
memory stick
memory cards
bluetooth
11a/b/g
UTMS

and multiple

standards

Dicom HL7 XML

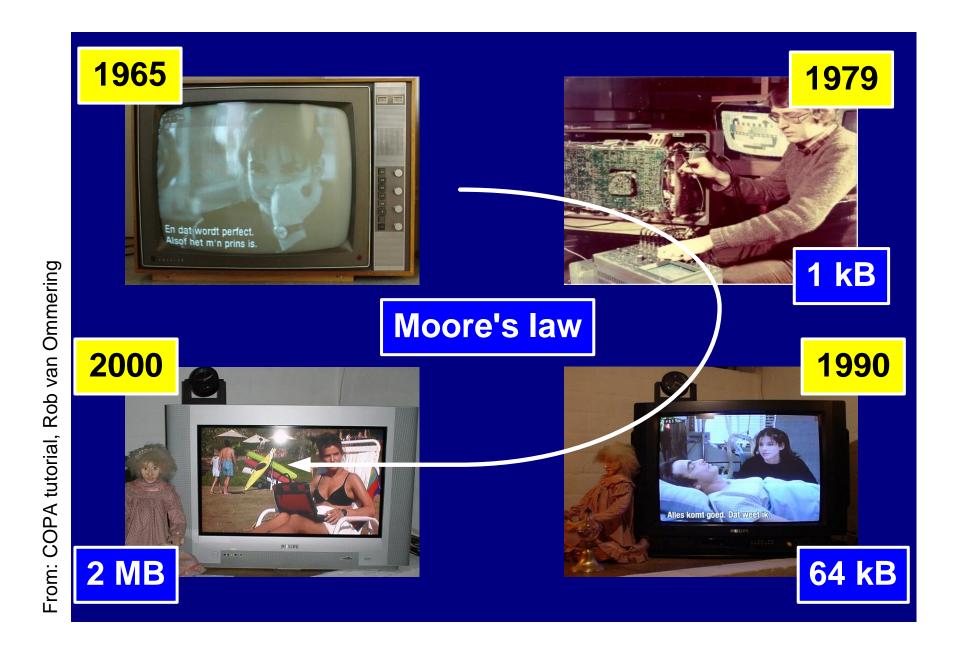
and multiple

releases

R5 R6.2 R7.1

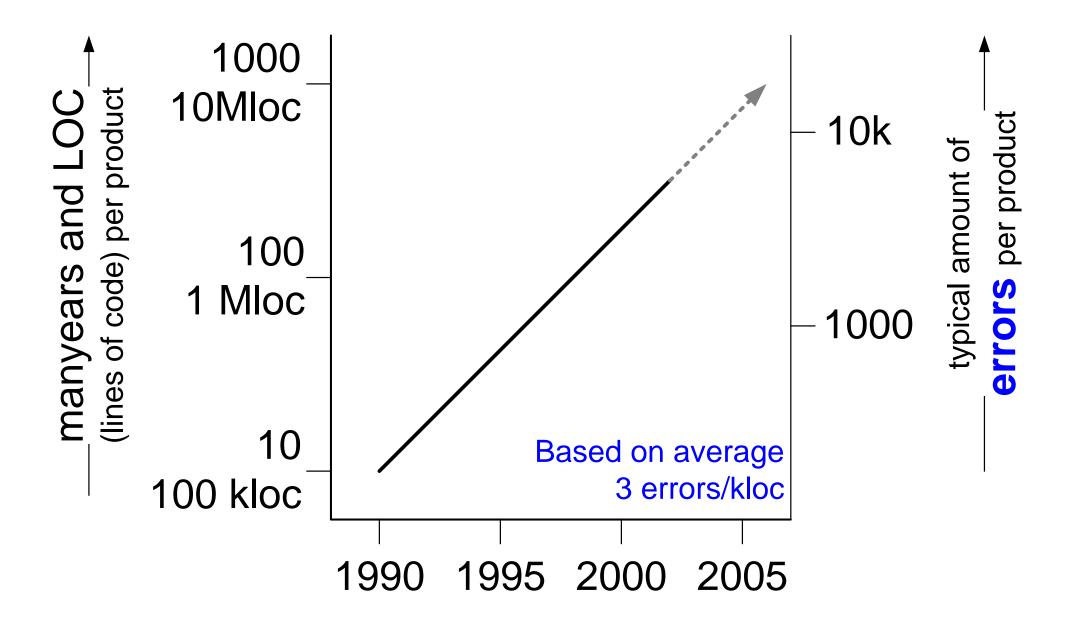


SW increase in televisions



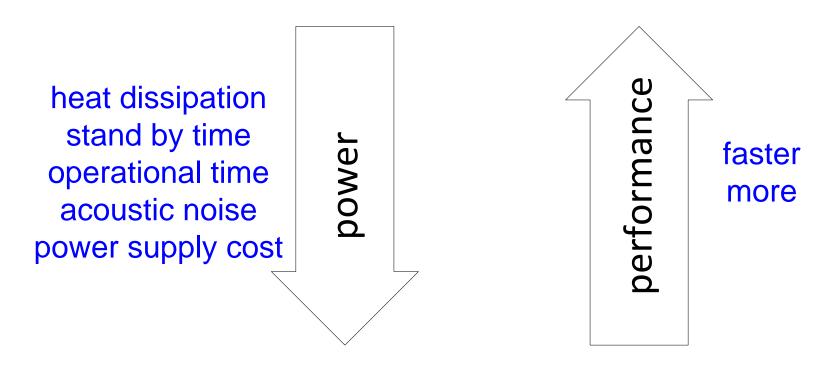


Increase of software threatens Reliability





Power consumption and dissipation



3G phone standby time operational time wireless video

examples

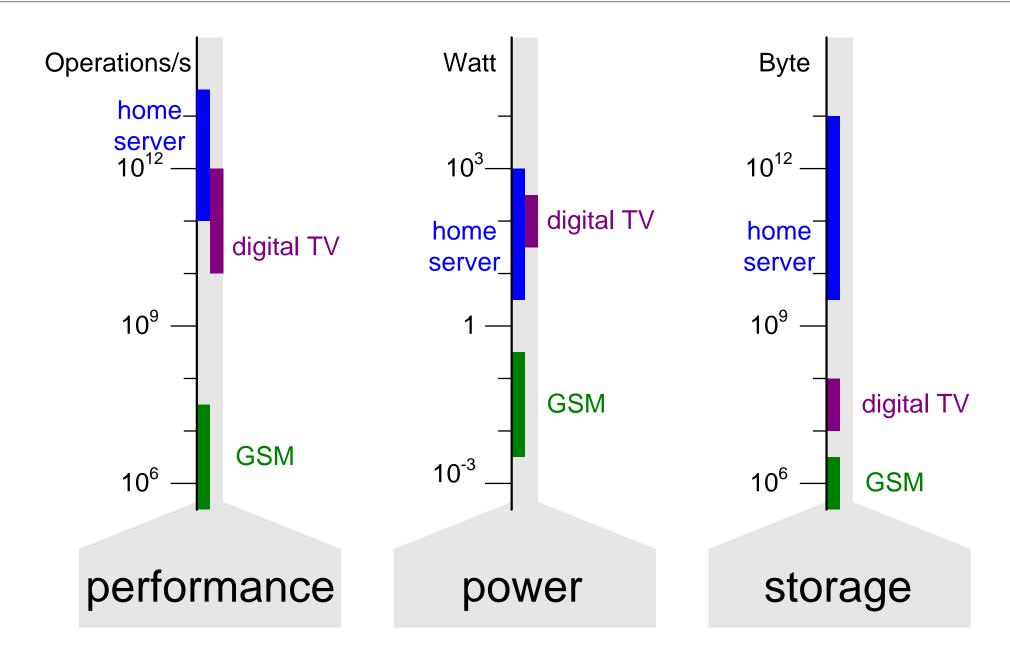
desktop silent fanless

data centers
insufficient power in
Amsterdam

MRI gradients: 66 mT/m kWatts: cost, noise, heat

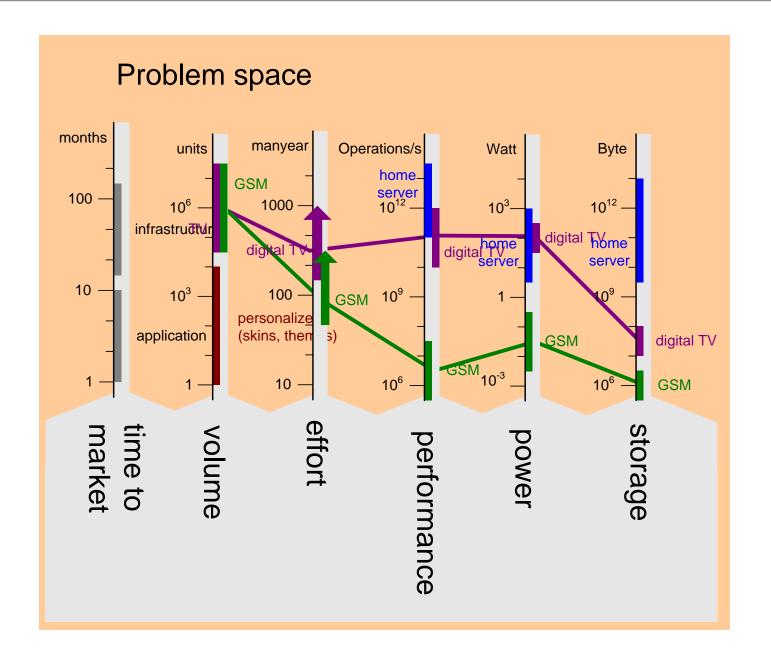


System Integrator Problem Space - Technology



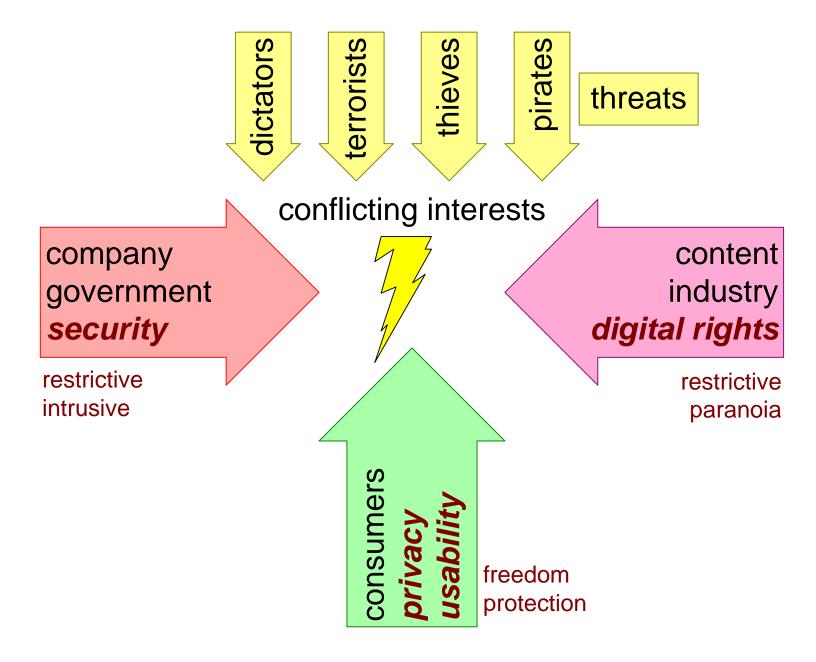


Profile of Digital TV and GSM



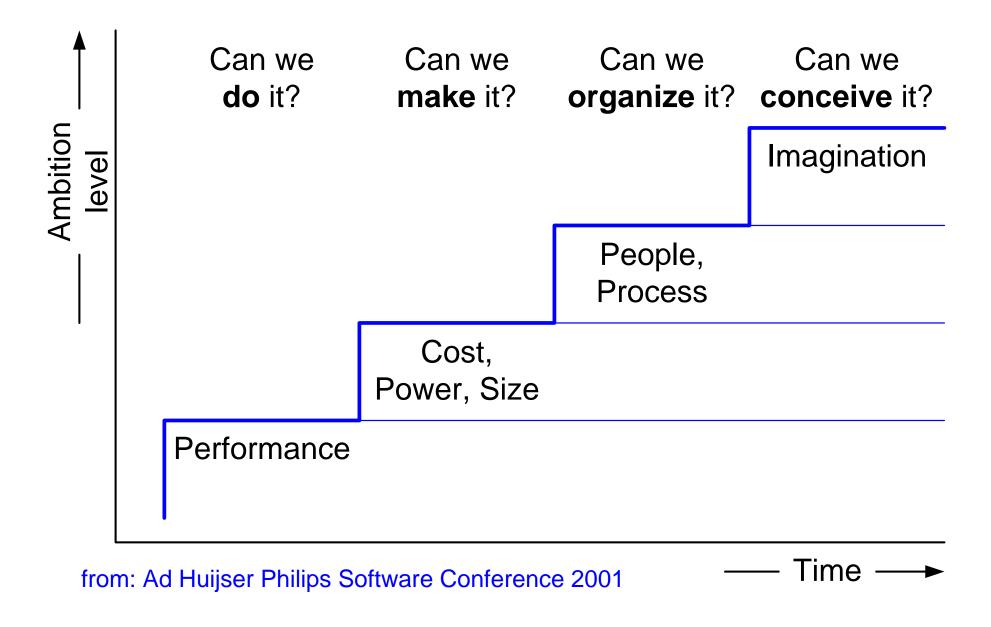


Security conflicting interests





Creativity as limiting factor





Role of Embedded Systems Institute ESI

